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PA

U.S. UTILITY Patent Application

APPL NUM 1081425	FILING DATE 02/22/2002	CLASS 188	SUBCLASS 27	GAU 282	EXAMINER
APPLICANT: Pendse Rajendra					

SBG

\*\* CONTINUING DATA VERIFIED:  
THIS APPLN CLAIMS BENEFIT OF 60/272,280 02/27/2001

\*\* FOREIGN APPLICATIONS VERIFIED:  
None

PG-PUB DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	CPAC 1011-2 US
35 USC 119 conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	
Verified and Acknowledged Examiners's initials SBG		
TITLE : Apparatus and process for precise encapsulation of flip chip interconnects		

NOTICE OF ALLOWANCE MAILED 5-8-03		DRAWINGS		CLAIMS ALLOWED	
ISSUE FEE		Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims Print Claim for O.G.
Amount Due \$ 1600	Date Paid 5/11/03				
<input type="checkbox"/> TERMINAL <input type="checkbox"/> DISCLAIMER				NOTICE OF ALLOWANCE MAILED	
Foreign Drawings:				ISSUE FEE	
				Amount Due	Date Paid
				ISSUE BATCH NUMBER	
				FILED WITH: <input type="checkbox"/> DISK (CRF) <input type="checkbox"/> CD-ROM (Attached in pocket on right inside flap)	